

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHUN-HAO TSENG</td> <td>10/17/2013</td> </tr> <tr> <td>YING-HAO KUO</td> <td>10/22/2013</td> </tr> <tr> <td>KUO-CHUNG YEE</td> <td>10/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHUN-HAO TSENG	10/17/2013	YING-HAO KUO	10/22/2013	KUO-CHUNG YEE	10/22/2013
Name	Execution Date								
CHUN-HAO TSENG	10/17/2013								
YING-HAO KUO	10/22/2013								
KUO-CHUNG YEE	10/22/2013								
RECEIVING PARTY DATA									
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.								
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK								
City:	HSINCHU								
State/Country:	TAIWAN								
Postal Code:	300								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14076487</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14076487				
Property Type	Number								
Application Number:	14076487								
CORRESPONDENCE DATA									
Fax Number:	(703)518-5499								
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NAME OF SUBMITTER:	RANDY A. NORANBROCK								
Signature:	/Randy A. Noranbrock/								
Date:	11/11/2013								
Total Attachments: 1 source=EfiledAssgn#page1.tif									

OP \$40.00 14076487

### ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Chun-Hao TSENG
- 2) Ying-Hao KUO
- 3) Kuo-Chung YEE

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

**THERMALLY CONDUCTIVE MOLDING COMPOUND STRUCTURE FOR HEAT DISSIPATION IN SEMICONDUCTOR PACKAGES**

(a) for which an application for United States Letters Patent was filed on 2013-11-11, and identified by United States Patent Application No. 14/076,487; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chun-Hao Tseng  
Name: Chun-Hao TSENG

2013.10.17.  
Date:

2) Ying-Hao Kuo  
Name: Ying-Hao KUO

2013.10.22  
Date:

2) Kuo-Chung Yee  
Name: Kuo-Chung YEE

2013.10.22  
Date: